

Characterisation of powder metallurgy Cu-ZrO₂ composites

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ABSTRACT

Cu-ZrO₂ composites can be used as electrical contact materials in relays, contactors, switches, circuit breakers, electronic packaging requiring good electrical and thermal conductivity as well as welding or brazing properties. In the presented work copper matrix composites reinforced with 8 mol % yttria-stabilised 1 wt. %, 2 wt. %, 3 wt. %, 4 wt. %, and 5 wt. % zirconia (8-YSZ) particles were fabricated by the powder metallurgy method. Cu and Cu-ZrO₂ powder mixtures were compacted with a compressive force of 500 MPa and sintered at 900 °C for 2 h within an argon atmosphere. The results of the study on the mechanical properties of the composites showed that with increasing content of ZrO₂, the micro-hardness and compressive strength increase. The relative densities of the composites decreased from 96.1 % to 92.0 % with increasing zirconia content up to 5 wt. %. The results of the electrical test on the composites indicated that electrical conductivity reduced gradually with increase in reinforcement content. SEM and EDS studies showed that Cu-ZrO₂ composites have a uniform microstructure in which zirconia particles are distributed uniformly in the Cu matrix.

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References

- [1] Rajabi, M. (2003). Characterisation of Al-SiC composite materials produced by double pressing-double sintering method, *International Journal of Engineering Science*, Vol. 14, No. 2, 21-37.
- [2] Callister, W.D. (2007). *Materials science and engineering*, John Wiley & Sons, New York.
- [3] Andić, Z., Tasić, M., Korać, M., Jordović, B., Maričić, A. (2004). Influence of alumina content on the sinterability of the Cu-Al₂O₃ pseudo alloy (composite), *Materiali in tehnologije/Materials and Technology*, Vol. 38, No. 5, 245-248.
- [4] Zhu, J., Liu, L., Zhao, H., Shen, B., Hu, W. (2007). Microstructure and performance of electroformed Cu/nano-SiC composite, *Materials and Design*, Vol. 28, 1958-1962, doi: 10.1016/j.matdes.2006.04.021.
- [5] Dhokey, N.B., Paretkar, R.K. (2008). Study of wear mechanisms in copper-based SiCp (20% by volume) reinforced composite, *Wear*, Vol. 265, No. 1-2, 117-133, doi: 10.1016/j.wear.2007.09.001.
- [6] Tjong, S.C., Lau, K.C. (2000). Abrasive wear behavior of TiB₂ particle-reinforced copper matrix composites, *Materials Science and Engineering: A*, Vol. 282, No. 1-2, 183-186, doi: 10.1016/S0921-5093(99)00752-2.
- [7] He, J., Zhao, N., Shi, C., Du, X., Li, J., Nash, P. (2008). Reinforcing copper matrix composites through molecular-level mixing of functionalised nanodiamond by co-deposition route, *Materials Science and Engineering A*, Vol. 490, No. 1-2, 293-299, doi: 10.1016/j.msea.2008.01.046.
- [8] Zhan, Y., Zhang, G. (2003). The effect of interfacial modifying on the mechanical and wear properties of SiCp/Cu composites, *Materials Letters*, Vol. 57, No. 29, 4583-4591, doi: 10.1016/S0167-577X(03)00365-3.
- [9] Wu, Y.J., Su, S.H., Wu, S.Y., Chen, X.M. (2011). Microstructures and dielectric properties of spark plasma sintered Ba_{0.4}Sr_{0.6}TiO₃/CaCu₃Ti₄O₁₂ composite ceramics, *Ceramics International*, Vol. 37, No. 6, 1979-1983, doi: 10.1016/j.ceramint.2011.02.006.
- [10] Yan, X.H., Qiu, J., Wang, C.S., Zhang, C.H., Cheng, X.N. (2008). Preparation of Cu coated ZrW₂O₈ composite powders via heterogeneous precipitation process, *Key Engineering Materials*, Vol. 368-372, 1377-1379, doi: 10.4028/www.scientific.net/KEM.368-372.1377.
- [11] Xue, Z.W., Liu, Z., Wang, L.D., Fei, W.D. (2010). Thermal properties of new copper matrix composite reinforced by β-eucryptite particulates, *Materials Science and Technology*, Vol. 26, No. 12, 1521-1524, doi: 10.1179/174328409X428927.

- [12] Ramaswamy, V., Bhagwat, M., Srinivas, D., Ramaswamy, A.V. (2004). Structural and spectral features of nano-crystalline copper-stabilized zirconia, *Catalysis Today*, Vol. 97, No. 1, 63-70.
- [13] Leistner, H., Ratcliffe, D., Schuler, A. (1991). *Improved material and design refractories*, Verlag Stahleisen., Dusseldorf, Germany.
- [14] Tjong, S.C., Ma, Z.Y. (2000). Microstructural and mechanical characteristic of in situ metal matrix composites, *Materials Science and Engineering: R: Reports*, Vol. 29, No. 3-4, 49-113, doi: 10.1016/S0927-796X(00)00024-3.
- [15] Costa, F.A., Silva, A.G.P., Silva Júnior, J.F., Gomes, U.U. (2008). Composite Ta-Cu powders prepared by high energy milling, *International Journal of Refractory Metals & Hard Materials*, Vol. 26, No. 6, 499-503, doi: 10.1016/j.ijrmhm.2007.12.002.
- [16] Towle, D. J., Friend, C. M. (1993). Comparison of compressive and tensile properties of Mg based MMCs, *Materials Science and Technology*, Vol. 9, No. 1, 35-41.
- [17] Celebi Efe, G.F. (2010). Development of conductive copper composites reinforced with SiC, Ph.D. thesis, Sakarya University, Turkey.
- [18] Liang, S., Fan, Z., Xu, L., Fang, L. (2004). Kinetic analysis on Al₂O₃/Cu nanocomposite prepared by mechanical activation and internal oxidation, *Composites Part A: Applied Science and Manufacturing*, Vol. 35, No. 12, 1441-1446, doi: 10.1016/j.compositesa.2004.04.008.
- [19] Hwang, S.J. (2011). Compressive yield strength of the Nano-crystalline Cu with Al₂O₃ dispersoid, *Journal of Alloys and Compounds*, Vol. 509, No. 5, 2355-2359, doi: 10.1016/j.jallcom.2010.11.017.
- [20] Reed Hill, R.E. (1964). *Improved material and design refractories*, D. Van Nostrand Company, UK.
- [21] Hemanth, J. (2009). Development and property evaluation of aluminum alloy reinforced with nano-ZrO₂ metal matrix nanocomposites (NMMCs), *Materials Science and Engineering: A*, Vol. 507, No. 1-2, 110-113, doi: 10.1016/j.msea.2008.11.039.